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Information Disclosure Statement by Applicant						Applicant: Christopher J. Diorio			
(Use several sheets if necessary)						Filed: March 30, 2004		Group: 2827	
U.S. Patent Documents									
Init.		Document No.	Date	Name	Class	Subclass	Filing Date		
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Init.		Document No.	Date	Country	Class	Subclass	Yes	No	
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SM	R	Declercq et al., "Design and Optimization of High-Voltage CMOS Devices Compatible With a Standard 5 V CMOS Technology", IEEE Custom Integrated Circuits Conference, 1993, pp. 24.6.1-24.6.4.							
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SM	T	Invitation to Pay Additional Fees for PCT/US 03/31792 date of mailing April 2, 2004.							
Examiner					Date Considered				
/Son Mai/ (04/26/2006)					04/26/2006				
Examiner: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include a copy of this form with the next communication to applicant.									

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